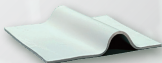


FIBCOOL High Thermal Conductivity Type

"Industry-leading thermal conductivity and flexibility"
Optimal filler design achieves both properties simultaneously!



Customizable

Size

Thickness

Hardness

Adhesive

Item	Unit	Characteristic Value
Thickness	mm	0.5, 1.0
Thermal Conductivity	W/m · K	12.5
Thermal Resistance	°C · cm ² / W	0.40 (at 350kPa)
Density	g/ cm ³	2.26
Hardness	°	50 (Shore OO)
Dielectric Strength	kV/mm	10.7 (at 0.1mm)
Dielectric Constant	-	8.9 (1MHz)
Dielectric Loss Tangent	-	3.1 × 10 ⁻² (1MHz)

(*) These are measured values, not product specification values.

Features

High Thermal Conductivity
12.5 W/m · K

Flexible
absorb tolerance

Resilient
Shape retention
high reliability

Oil Free

Benefits

- 01 Maximize high output performance through improved heat dissipation
- 02 Able to adapt to component height differences.
- 03 Improve work efficiency and reduce costs!
- 04 Follows thermal expansion and external stress of components
- 05 Maintain low thermal resistance, high reliability!
- 06 Maintain performance of mounted components!

Applications

Power Modules



Motor Drive Units



Communication Module ICs



CPU

